## THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:		§	Patent No.:	6821829			
PEATMAN, WILLIAM C., et al.		§ a	T D /	11/02/2004			
		§	Issue Date:	11/23/2004			
Application No.: 09/592349		§					
		§	Examiner:	Douglass Wille			
Filed:	6/12/2000	§					
		§	§ Group Art Unit: 2814				
Docket No.: SC11100ZP		§					
		§					
Title: METHOD OF MANUFACTURING A SEMICONDUCTOR COMPONENT A SEMICONDUCTOR COMPONENT THEREOF							
			I hereby certify that this correspondence is being submitted to the U.S.P.T.O., Alexandria, VA.				
		United	Addressed per C.F.R.§ 1.1(a) and deposited with the United States Postal Service with sufficient postage as first class mail.				
			Facsimile transmitted in accordance with C.F.R.§1.6(d).				
	$\underline{X}$ Submitted electronically via EFS in accordance with "Legal Framework for EFS Web".						
		9.20.06					
			Date of Submission				
		Signature					
		Pat Thomas					
			Printed Name of Person Signing Certificate				

Commissioner for Patents Alexandria, VA 22313

## SUBMISSION OF CERTIFICATE OF CORRECTION

## Dear Commissioner:

Enclosed is a Certificate of Correction listing error(s) in the subject patent. Please enter these corrections which were made in an Examiner's amendment. Since the errors appear to be on the part of the United States Patent Office, there should be no charge.

Date

Respectfully submitted,

Michael J. Balconi-Lamica Attorney for Applicant(s) Registration No. 34,291

Telephone No. (512) 996-6839 Facsimile No. (512) 996-6854 Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it displays a valid OMB control number.

(Also Form PTO-1050)

## UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

CERTIFICATE OF CORRECTION									
				Page <u>1</u>	of1				
PATENT NO.:	6821829								
APPLICATION NO:	09/592349								
DATE:	11/23/2004								
INVENTOR(S):	PEATMAN, WIL	LIAM C.							
It is certified that error a	ppears in the above-i	dentified pate	ent and that sa	id Letters Pat	ent are				
hereby corrected as show	n below:								
In Column 8, After Line									
	dielectric layer over								
undoped gallium arsenic	le capping layer and t	the exposed p	ortion of the s	surface of the	delta-doped				
heteroepitoxial semiconductor substrate;"									
	•								

MAILING ADDRESS OF SENDER (Please do not use customer number below)

Freescale Semiconductor, Inc. Law Department 7700 West Parmer Lane PL02 Austin, TX 78729